

P-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)	Q_g (Typ.)
- 40	0.011 at $V_{GS} = - 10$ V	- 65 ^d	50
	0.015 at $V_{GS} = - 4.5$ V	- 53 ^d	

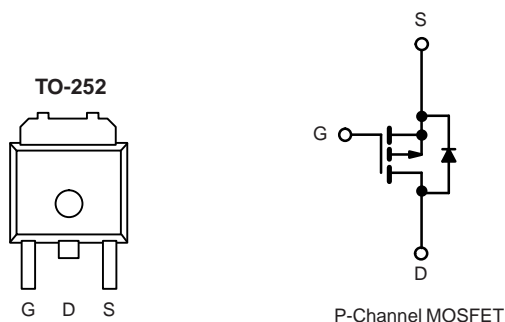
FEATURES

- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC


RoHS
 COMPLIANT

APPLICATIONS

- Power Switch
- Load Switch in High Current Applications
- DC/DC Converters



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 40	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150\text{ }^\circ\text{C}$)	I_D	- 65 ^d	A
		- 58 ^d	
Pulsed Drain Current	I_{DM}	- 195	
Avalanche Current	I_{AS}	- 66	
Single Avalanche Energy ^a	E_{AS}	105	mJ
Maximum Power Dissipation ^a	P_D	75 ^b	W
		2.5	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) ^c	R_{thJA}	50	$^\circ\text{C/W}$
Junction-to-Case (Drain)	R_{thJC}	1.7	

Notes:

- Duty cycle $\leq 1\%$.
- See SOA curve for voltage derating.
- When Mounted on 1" square PCB (FR-4 material).
- Package limited.

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{DS} = 0\text{ V}$, $I_D = -250\text{ }\mu\text{A}$	- 40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = -250\text{ }\mu\text{A}$	- 1		- 2.5	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 250	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -32\text{ V}$, $V_{GS} = 0\text{ V}$			- 1	μA
		$V_{DS} = -32\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$			- 50	
		$V_{DS} = -32\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 150\text{ }^{\circ}\text{C}$			- 250	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \leq -10\text{ V}$, $V_{GS} = -10\text{ V}$	- 50			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$, $I_D = -20\text{ A}$		0.011	0.013	Ω
		$V_{GS} = -4.5\text{ V}$, $I_D = -15\text{ A}$		0.015	0.018	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -15\text{ V}$, $I_D = -20\text{ A}$		46		S
Dynamic ^b						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}$, $V_{DS} = -20\text{ V}$, $f = 1\text{ MHz}$		3085		pF
Output Capacitance	C_{oss}			510		
Reverse Transfer Capacitance	C_{rss}			200		
Total Gate Charge ^c	Q_g	$V_{DS} = -20\text{ V}$, $V_{GS} = -10\text{ V}$, $I_D = -20\text{ A}$		50	58	nC
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = -20\text{ V}$, $V_{GS} = -4.5\text{ V}$, $I_D = -20\text{ A}$		22		
Gate-Drain Charge ^c	Q_{gd}			10		
Gate Resistance	R_g	$f = 1\text{ MHz}$	1.8	3	5.2	
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = -20\text{ V}$, $R_L = 2\text{ }\Omega$ $I_D \cong -10\text{ A}$, $V_{GEN} = -10\text{ V}$, $R_g = 1\text{ }\Omega$		11		ns
Rise Time ^c	t_r			24		
Turn-Off Delay Time ^c	$t_{d(off)}$			60		
Fall Time ^c	t_f			28		
Drain-Source Body Diode Ratings and Characteristics $T_C = 25\text{ }^{\circ}\text{C}$ ^b						
Continuous Current	I_S				- 65	A
Pulsed Current	I_{SM}				- 195	
Forward Voltage ^a	V_{SD}	$I_F = -10\text{ A}$, $V_{GS} = 0\text{ V}$		- 0.8	- 1.5	V
Reverse Recovery Time	t_{rr}	$I_F = -10\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}$		35	53	ns
Peak Reverse Recovery Current	$I_{RM(REC)}$			- 2	- 3	A
Reverse Recovery Charge	Q_{rr}			33	50	nC

Notes:

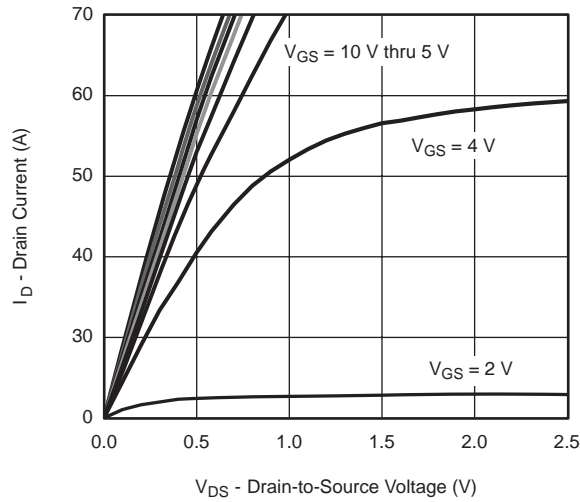
a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

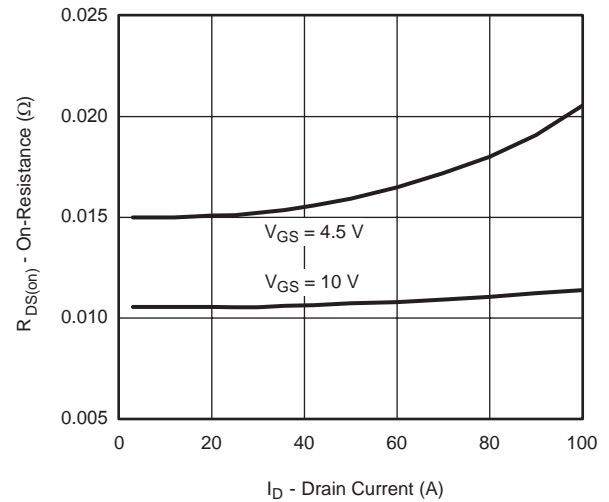
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

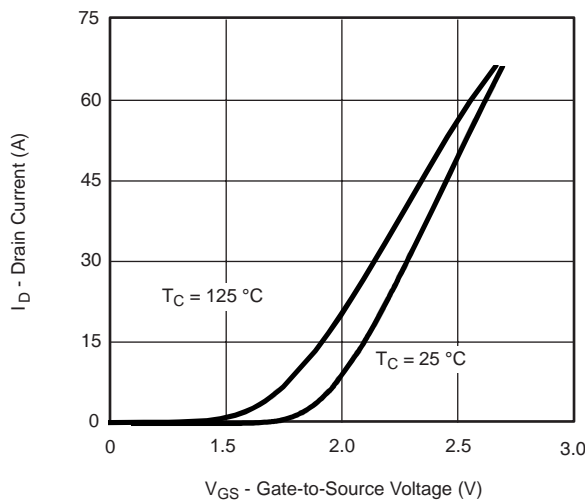
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



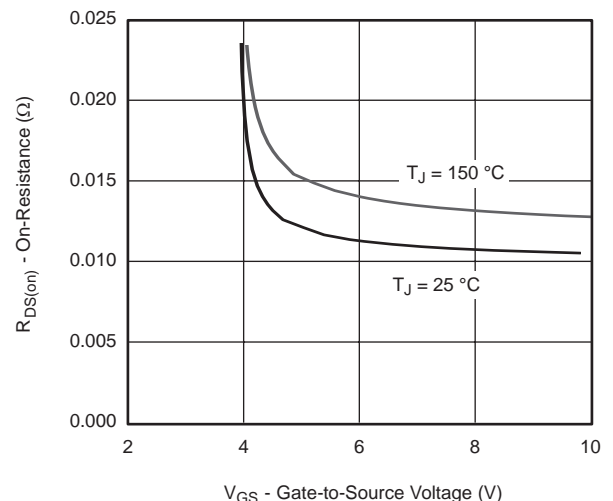
Output Characteristics



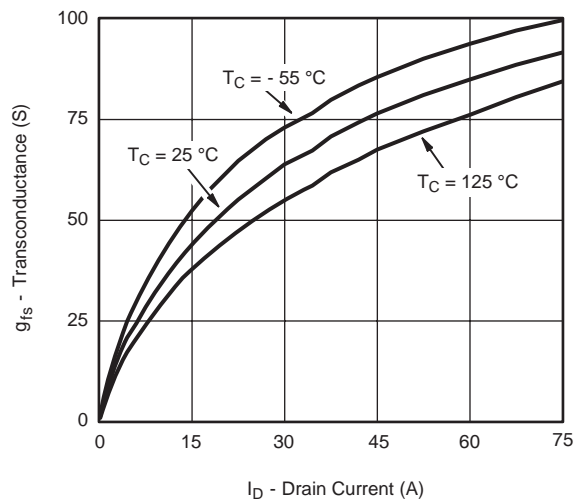
On-Resistance vs. Drain Current



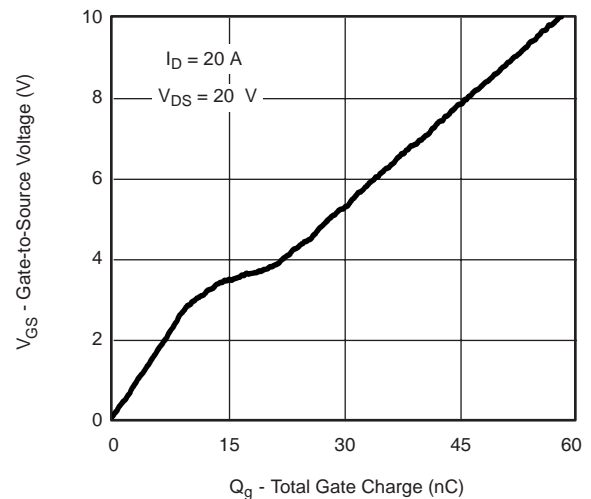
Transfer Characteristics



On-Resistance vs. Gate-to-Source Voltage

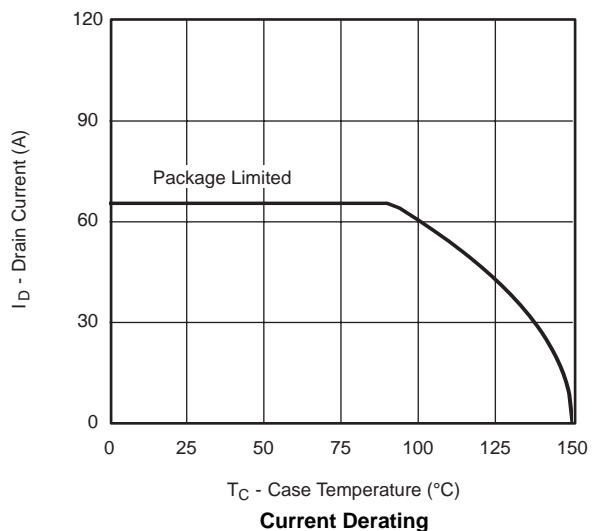
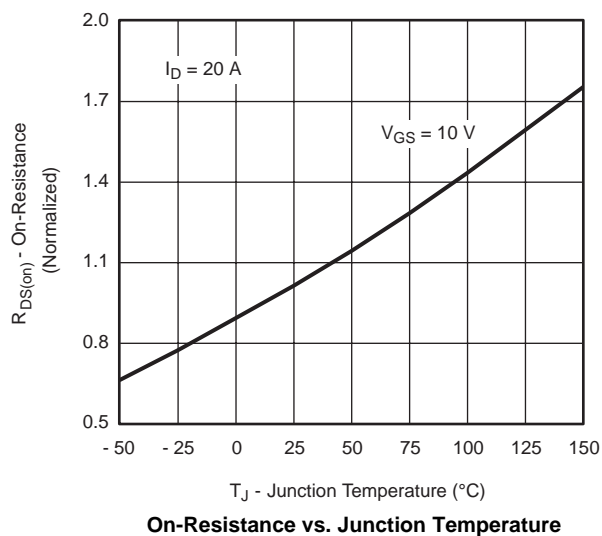
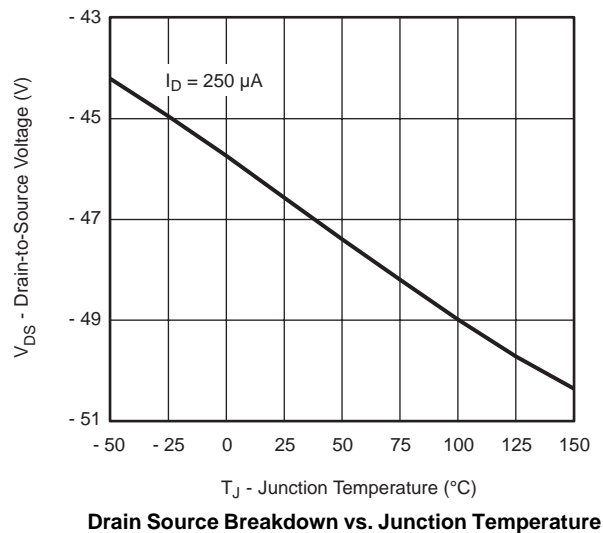
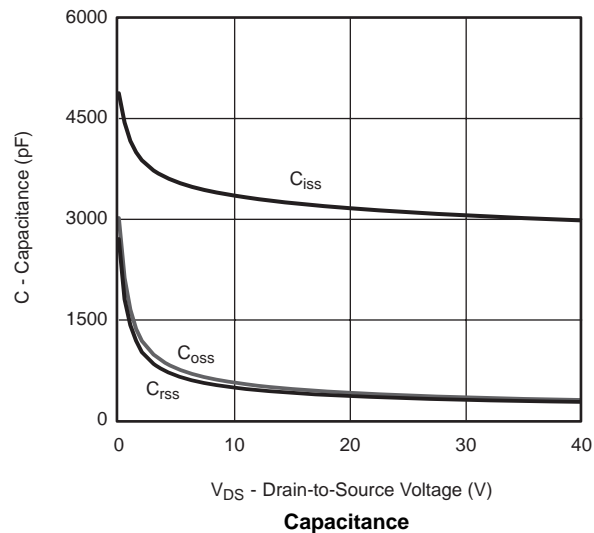
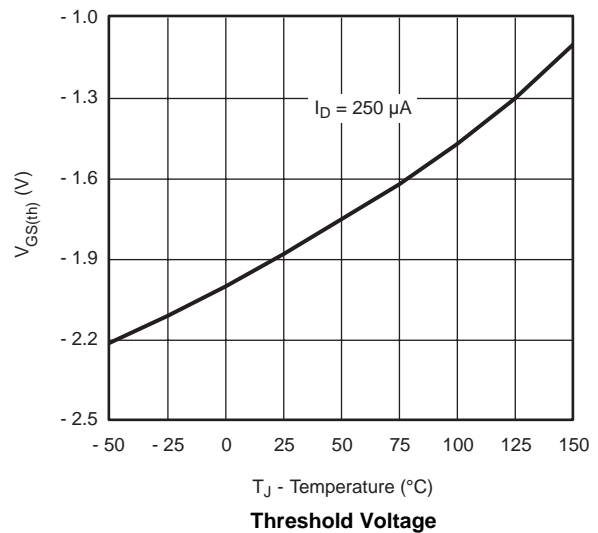
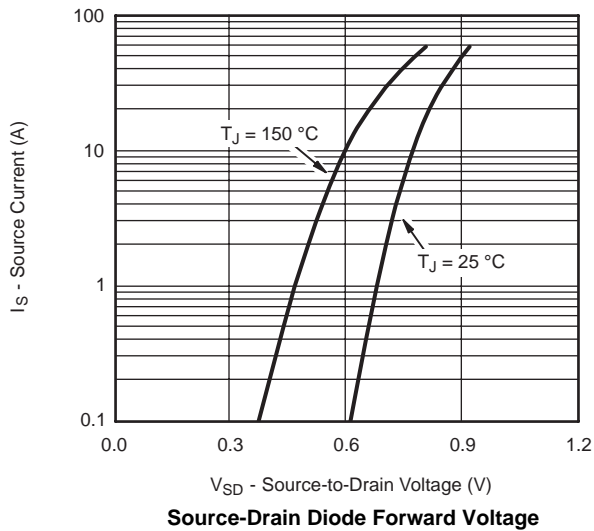


Transconductance

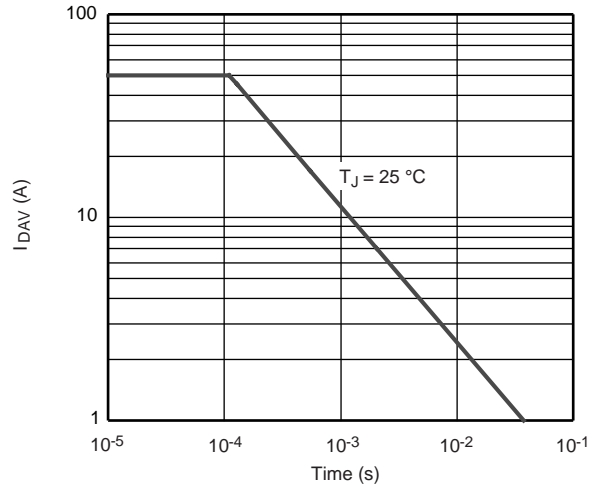


Gate Charge

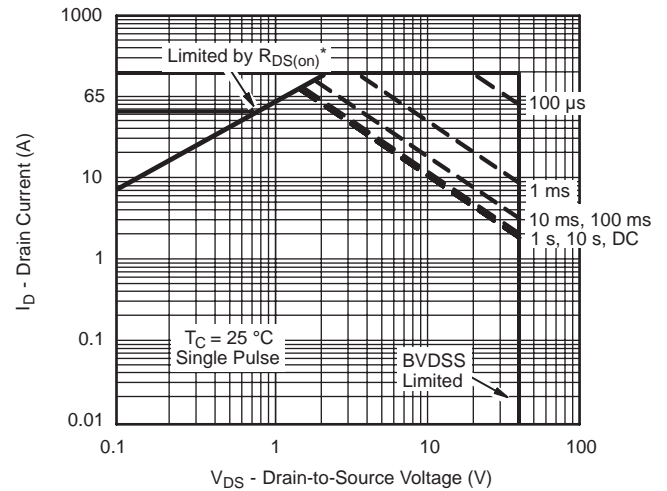
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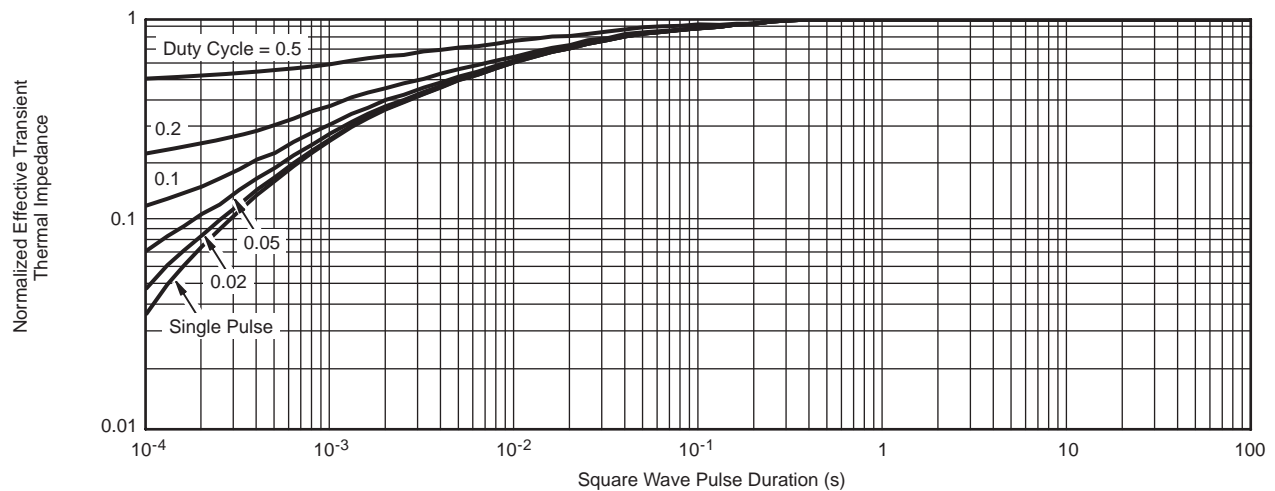


Single Pulse Avalanche Current Capability vs. Time



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

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